

High Performance InGaAs p-i-n Photodiode

'FC' Active Device Mount

13PD300-FC

The 13PD300-FC, an InGaAs photodiode with a 300 μ m-diameter photosensitive region packaged in a TO-46 header and aligned in an FC active device mount, is designed for applications in both moderate-bit-rate fiberoptic communications and high sensitivity measurement equipment. This device is one of the most versatile of the Telcom Devices' family of optoelectronic components. Planar semiconductor design and dielectric passivation provide superior performance. Reliability is assured by hermetic sealing and a 100% purge burn-in (200°C, 15 hours, V_r = 20V).

Features

Planar Structure Dielectric Passivation 100% Purge Burn-In High Responsivity

Device Characteristics:							
Parameters	Test Conditions		Min	Тур	Max	Units	
Operating Voltage	-		-	-	-20	Volts	
Dark Current	-5V	-	1.0	10	n A		
Capacitance	-5V	-	4	12	2 pl	F	
Responsivity	1300nm		0.7	0.9	-	A/W	
Rise/Fall	-		-	-	0.5	ns	
Frequency Respon	se (-3dB)		-	300	-	MHz	
Absolute Maximum Ratings							
Reverse Voltage				30 Volts			
Forward Current				25 mA			
Reverse Current				5 mA			
Operating Temperature				$-40^{\circ}\mathrm{C}$ to $+85^{\circ}\mathrm{C}$			
Storage Temperature				$-40^{\circ}\mathrm{C} \text{ to} + 85^{\circ}\mathrm{C}$			
Soldering Temperature				250°C			